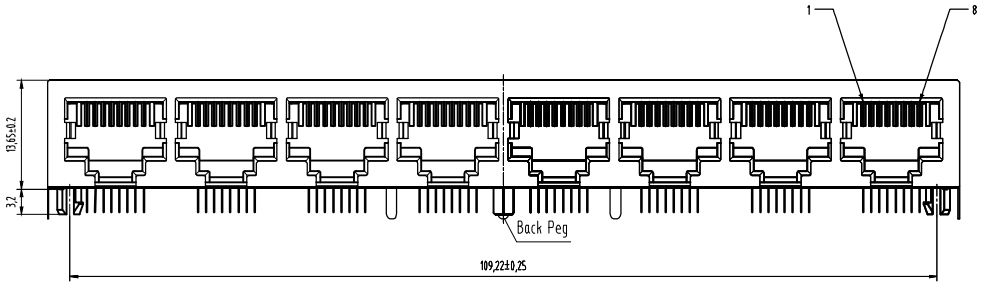
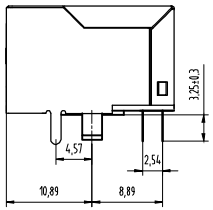
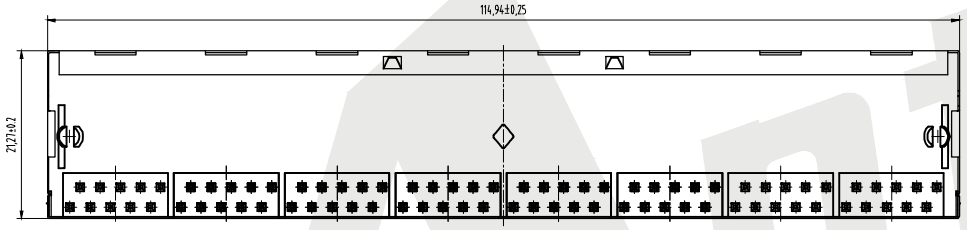
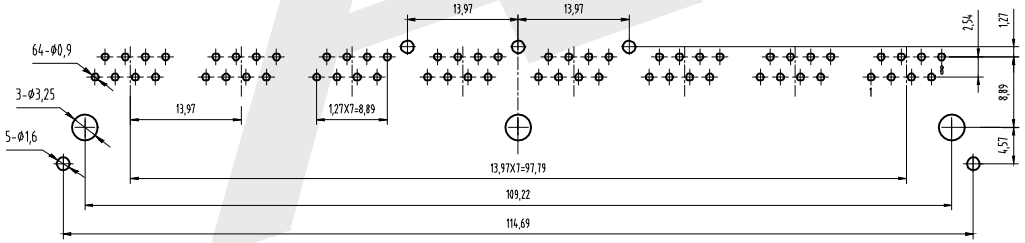
HSF Pb RoHS









PC Board Layout

Component Side Shown

NOTES:
MATERIAL:
1. HOUSING MATERIAL:GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL:PHOSPHOR BRONZE t=0.3mm
3. PLATING:SELECTING GOLD PLATING 1μ~50μ"OVER NICKEL IN CONTACT AREA.150μ" TIN PLATIN.OVER NICKEL IN SOLDER AREA
4. SHIELD:0.2mmTHICKNESS COPPER WITH NICKEL PLATEI

ELECTRICAL
1. VOLTAGE RATING:125V AC RMS
2. CURRENT RATING:1.5AMP
3. CONTACT RESISTANCE:30 MILLIOHMS MAX
4. INSULATION RESISTANCE 500 MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE :1000V AC RMS 50Hz. 1MIN

MECHANICAL
1. DURRABILITY:750 CYCLES MIN
2. PCB RETENTTON PRB-SOLDER:1 LB MIN

REVIRONMENTAL
1. STORAGE:-40° C TO 85° C
2. OPERATION:0° C TO 70° C

Order code:

ATRJ5921 - 8P - 8C - X - D - F - C

① ② ③ ④ ⑤ ⑥ ⑦

① SERIES NO:
② NUMBER OF POSITIONS (10P, 8P, 6P, 4P)
③ NUMBER OF CONTACTS (10C, 8C, 6C, 4C)
④ Contact Plating
GO:GOld flash
G1: 3U" Gold
G2: 5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
SN:Tin
⑤ Shield
A:W/O Shield
B:Half Shield
C:Shield W/Eml
D:Shield W/O Eml
⑥ Ports
A:1X1P
B:1X2P
C:1X4P
D:1X5P
E:1X6P
F:1X8P
⑦ PCB layout style:
A:TYPE 1 front legs 3.05
B:TYPE 1 front legs 3.68
C:TYPE 1 front legs 4.57
D:TYPE 2 Back legs 3.05
E:TYPE 2 Back legs 3.68
F:TYPE 2 Back legs 4.57

REV	DESCRIPTION	DATE

Unless Otherwise specified tolerance
X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE: As Shown	UNIT: mm
DRAW Wu Feng Rong	DATE 22/03/2018
CHECK BobYang	DATE 22/03/2018

3rd ANGLE PROJECTION

ANTENK ELECTRONICS CO,.LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: RJ45 Jack side entry, Shielded, 1X8P Front 4.57

DRAWING NO: ATRJ5921-8P8C-X-D-F-C

PRODUCT NO: ATRJ5921-8P8C-X-D-F-C